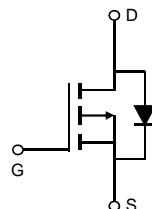


General Description

The AON2405 combines advanced trench MOSFET technology with a low resistance package to provide extremely low $R_{DS(ON)}$. This device is ideal for load switch and battery protection applications.

Features

| | |
|-----------------------------------|--------|
| V_{DS} | -20V |
| I_D (at $V_{GS}=-4.5V$) | -8A |
| $R_{DS(ON)}$ (at $V_{GS}=-4.5V$) | < 32mΩ |
| $R_{DS(ON)}$ (at $V_{GS}=-2.5V$) | < 41mΩ |
| $R_{DS(ON)}$ (at $V_{GS}=-1.8V$) | < 56mΩ |
| $R_{DS(ON)}$ (at $V_{GS}=-1.5V$) | < 70mΩ |



Absolute Maximum Ratings $T_A=25^\circ\text{C}$ unless otherwise noted

| Parameter | Symbol | Maximum | Units |
|--|----------------|------------|-------|
| Drain-Source Voltage | V_{DS} | -20 | V |
| Gate-Source Voltage | V_{GS} | ± 8 | V |
| Continuous Drain Current ^G | I_D | -8 | A |
| $T_A=70^\circ\text{C}$ | | -6 | |
| Pulsed Drain Current ^C | I_{DM} | -32 | A |
| Power Dissipation ^A | P_D | 2.8 | W |
| $T_A=70^\circ\text{C}$ | | 1.8 | |
| Junction and Storage Temperature Range | T_J, T_{STG} | -55 to 150 | °C |

Thermal Characteristics

| Parameter | Symbol | Typ | Max | Units |
|---|-----------------|-----|-----|-------|
| Maximum Junction-to-Ambient ^A $t \leq 10\text{s}$ | $R_{\theta JA}$ | 37 | 45 | °C/W |
| Maximum Junction-to-Ambient ^{AD} Steady-State | | 66 | 80 | °C/W |

Electrical Characteristics ($T_J=25^\circ\text{C}$ unless otherwise noted)

| Symbol | Parameter | Conditions | Min | Typ | Max | Units |
|-----------------------------|---------------------------------------|---|------|-------|-----------|------------------|
| STATIC PARAMETERS | | | | | | |
| BV_{DSS} | Drain-Source Breakdown Voltage | $I_D=-250\mu\text{A}, V_{GS}=0\text{V}$ | -20 | | | V |
| I_{DSS} | Zero Gate Voltage Drain Current | $V_{DS}=-20\text{V}, V_{GS}=0\text{V}$ $T_J=55^\circ\text{C}$ | | | -1 | μA |
| I_{GSS} | Gate-Body leakage current | $V_{DS}=0\text{V}, V_{GS}=\pm 8\text{V}$ | | | ± 100 | nA |
| $V_{\text{GS(th)}}$ | Gate Threshold Voltage | $V_{DS}=V_{GS}, I_D=-250\mu\text{A}$ | -0.3 | -0.65 | -0.9 | V |
| $I_{\text{D(ON)}}$ | On state drain current | $V_{GS}=-4.5\text{V}, V_{DS}=-5\text{V}$ | -32 | | | A |
| $R_{\text{DS(ON)}}$ | Static Drain-Source On-Resistance | $V_{GS}=-4.5\text{V}, I_D=-8\text{A}$ $T_J=125^\circ\text{C}$ | 26 | 32 | | $\text{m}\Omega$ |
| | | $V_{GS}=-2.5\text{V}, I_D=-5\text{A}$ | 35 | 43 | | $\text{m}\Omega$ |
| | | $V_{GS}=-1.8\text{V}, I_D=-2\text{A}$ | 41 | 56 | | $\text{m}\Omega$ |
| | | $V_{GS}=-1.5\text{V}, I_D=-2\text{A}$ | 46 | 70 | | $\text{m}\Omega$ |
| g_{FS} | Forward Transconductance | $V_{DS}=-5\text{V}, I_D=-8\text{A}$ | | 23 | | S |
| V_{SD} | Diode Forward Voltage | $I_S=-1\text{A}, V_{GS}=0\text{V}$ | | -0.62 | -1 | V |
| I_S | Maximum Body-Diode Continuous Current | | | | -4.5 | A |
| DYNAMIC PARAMETERS | | | | | | |
| C_{iss} | Input Capacitance | $V_{GS}=0\text{V}, V_{DS}=-10\text{V}, f=1\text{MHz}$ | | 1025 | | pF |
| C_{oss} | Output Capacitance | | | 167 | | pF |
| C_{rss} | Reverse Transfer Capacitance | | | 119 | | pF |
| R_g | Gate resistance | $V_{GS}=0\text{V}, V_{DS}=0\text{V}, f=1\text{MHz}$ | | 11 | | Ω |
| SWITCHING PARAMETERS | | | | | | |
| Q_g | Total Gate Charge | $V_{GS}=-4.5\text{V}, V_{DS}=-10\text{V}, I_D=-8\text{A}$ | | 13 | 18 | nC |
| Q_{gs} | Gate Source Charge | | | 2 | | nC |
| Q_{gd} | Gate Drain Charge | | | 3.4 | | nC |
| $t_{\text{D(on)}}$ | Turn-On Delay Time | $V_{GS}=-4.5\text{V}, V_{DS}=-10\text{V}, R_L=1.25\Omega, R_{\text{GEN}}=3\Omega$ | | 7 | | ns |
| t_r | Turn-On Rise Time | | | 28 | | ns |
| $t_{\text{D(off)}}$ | Turn-Off Delay Time | | | 95 | | ns |
| t_f | Turn-Off Fall Time | | | 46 | | ns |
| t_{rr} | Body Diode Reverse Recovery Time | $I_F=-8\text{A}, dI/dt=100\text{A}/\mu\text{s}$ | | 15 | | ns |
| Q_{rr} | Body Diode Reverse Recovery Charge | $I_F=-8\text{A}, dI/dt=100\text{A}/\mu\text{s}$ | | 4 | | nC |

A. The value of $R_{\theta JA}$ is measured with the device mounted on 1in² FR-4 board with 2oz. Copper, in a still air environment with $T_A=25^\circ\text{C}$. The Power dissipation P_{DSM} is based on $R_{\theta JA}$, $t \leq 10\text{s}$ value and the maximum allowed junction temperature of 150°C . The value in any given application depends on the user's specific board design.

B. The power dissipation P_D is based on $T_{J(\text{MAX})}=150^\circ\text{C}$, using junction-to-case thermal resistance, and is more useful in setting the upper dissipation limit for cases where additional heatsinking is used.

C. Repetitive rating, pulse width limited by junction temperature $T_{J(\text{MAX})}=150^\circ\text{C}$. Ratings are based on low frequency and duty cycles to keep initial $T_J=25^\circ\text{C}$.

D. The $R_{\theta JA}$ is the sum of the thermal impedance from junction to case $R_{\theta JC}$ and case to ambient.

E. The static characteristics in Figures 1 to 6 are obtained using <300μs pulses, duty cycle 0.5% max.

F. These curves are based on the junction-to-case thermal impedance which is measured with the device mounted to a large heatsink, assuming a maximum junction temperature of $T_{J(\text{MAX})}=150^\circ\text{C}$. The SOA curve provides a single pulse rating.

G. The maximum current rating is package limited.

H. These tests are performed with the device mounted on 1 in² FR-4 board with 2oz. Copper, in a still air environment with $T_A=25^\circ\text{C}$.

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

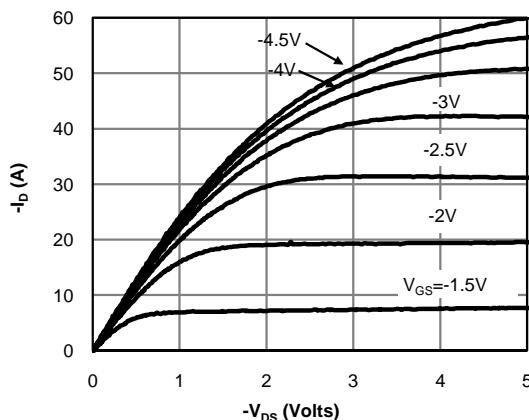


Fig 1: On-Region Characteristics (Note E)

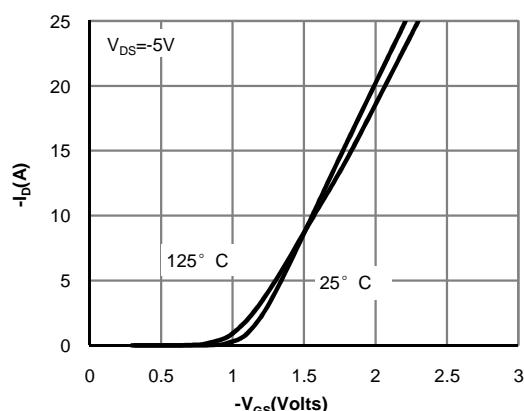


Figure 2: Transfer Characteristics (Note E)

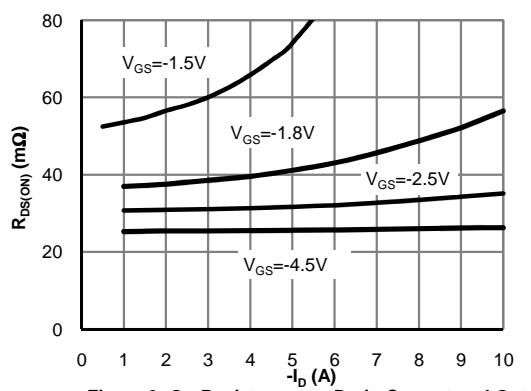


Figure 3: On-Resistance vs. Drain Current and Gate Voltage (Note E)

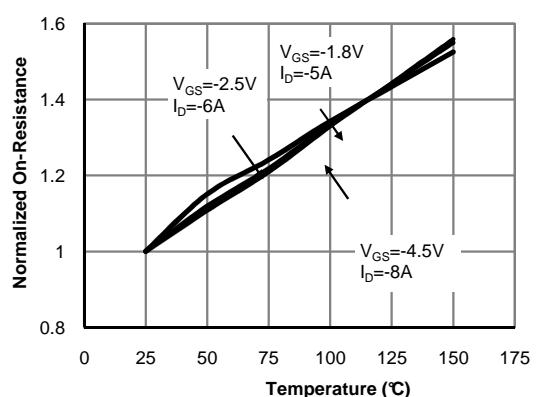


Figure 4: On-Resistance vs. Junction Temperature (Note E)

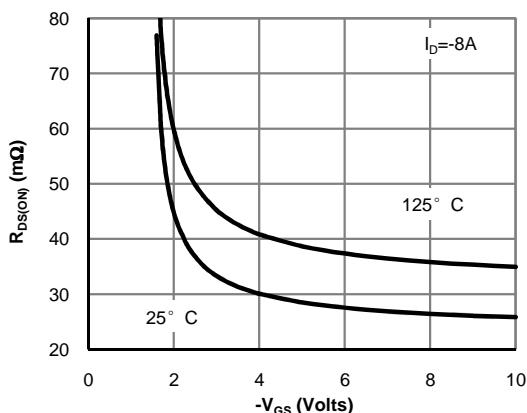


Figure 5: On-Resistance vs. Gate-Source Voltage (Note E)

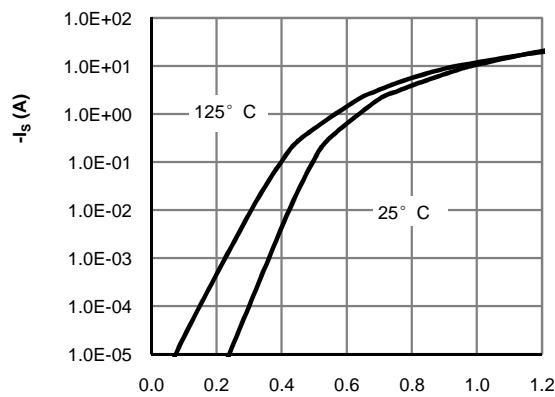


Figure 6: Body-Diode Characteristics (Note E)

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

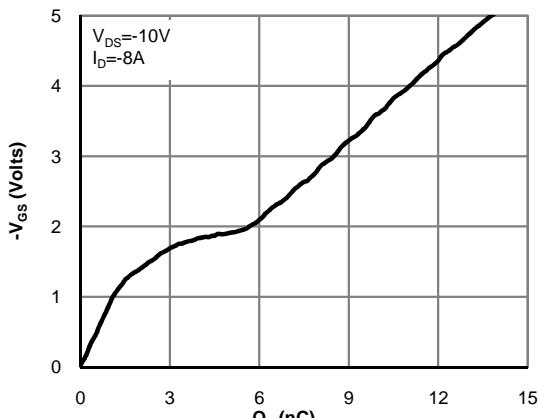


Figure 7: Gate-Charge Characteristics

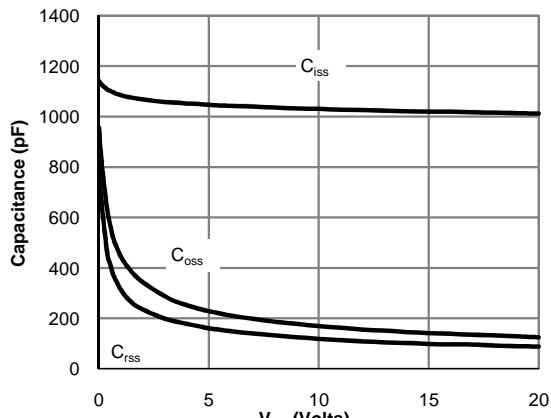


Figure 8: Capacitance Characteristics

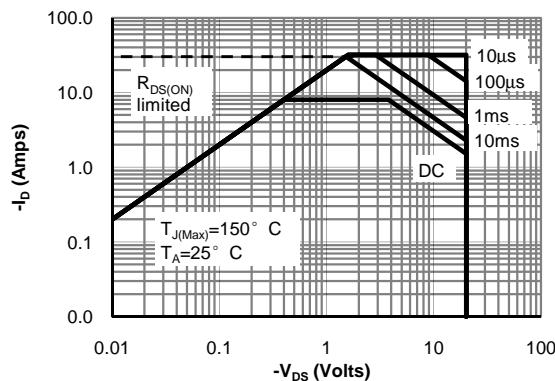


Figure 9: Maximum Forward Biased Safe Operating Area (Note F)

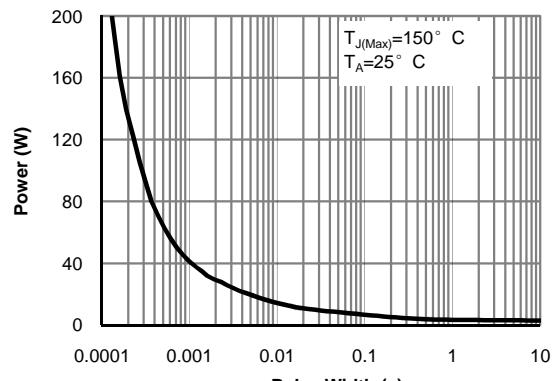
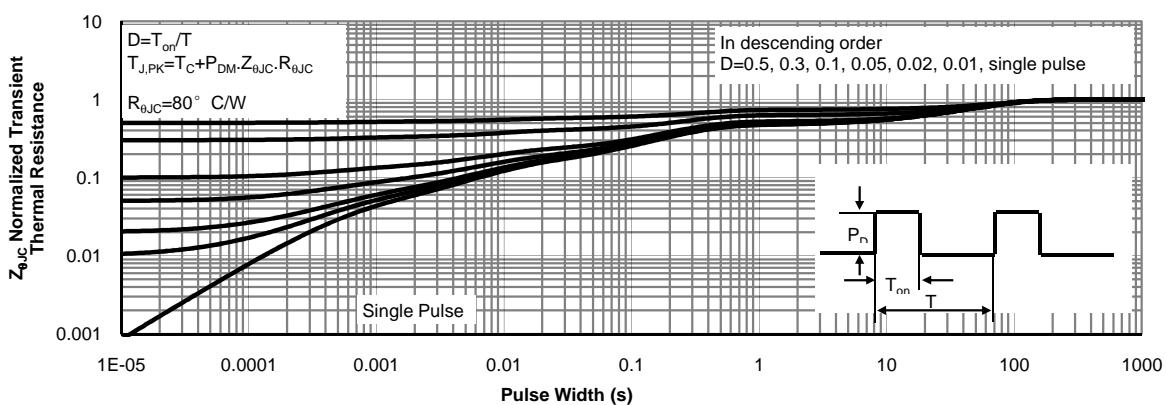
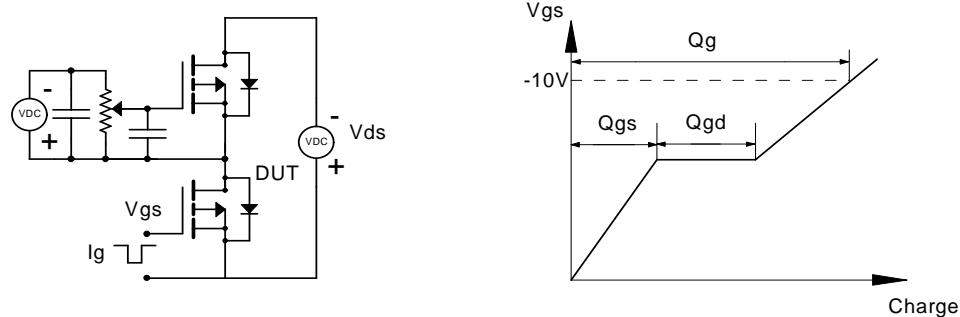


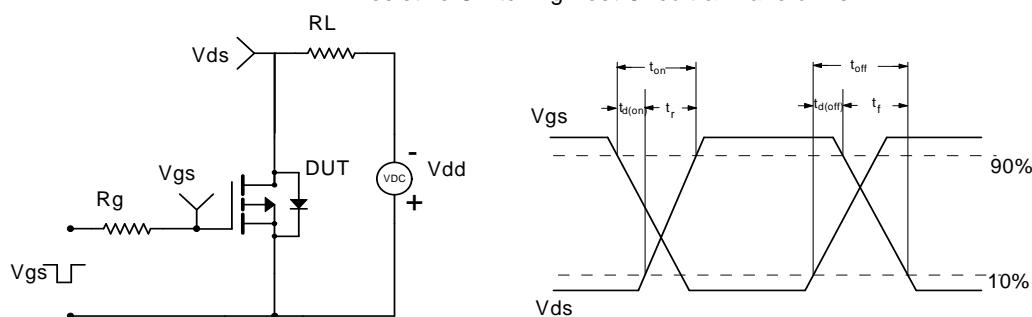
Figure 10: Single Pulse Power Rating Junction-to-Ambient (Note H)



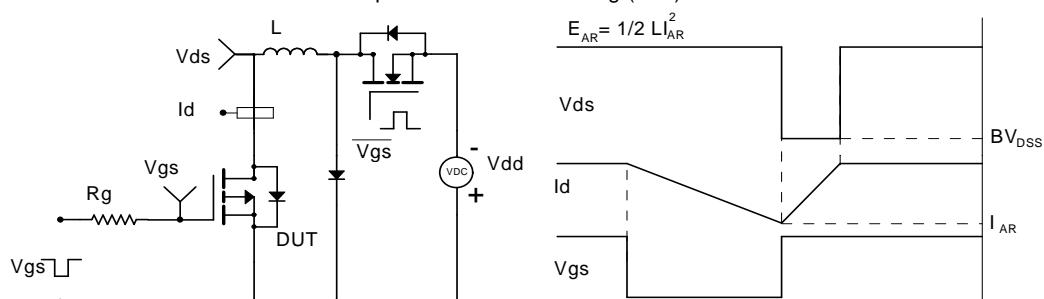
Gate Charge Test Circuit & Waveform



Resistive Switching Test Circuit & Waveforms



Unclamped Inductive Switching (UIS) Test Circuit & Waveforms



Diode Recovery Test Circuit & Waveforms

